Isolated DC/DC Converter

VIN: 3V to 5.2V

Read Design Guide

Primary Current

VIN

SW

Switch Node

ISOLATION

VIN

SW

Read Design Guide
### PCB Label

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>TIDA-00349 E1</td>
</tr>
</tbody>
</table>

### Assembly Notes

- ZZ1: These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ2: These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4: These assemblies must comply with workmanship standards (IPC-A-610 Class 2), unless otherwise specified.

### Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>ZZ5</td>
<td>Jumper/Shunt: SH-J4 on J4-PINs 2-3</td>
</tr>
<tr>
<td>ZZ6</td>
<td>Jumper/Shunt: SH-J5 on J5-PINs 2-3</td>
</tr>
<tr>
<td>ZZ7</td>
<td>Jumper/Shunt: SH-J6 on J6-PINs 1-2</td>
</tr>
</tbody>
</table>

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